



**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**  
(Attorney Docket No. 4492P1072US; Client No. P97-0013US3)

Applicant: Batz et al

For: METHODS FOR PLATING SEMICONDUCTOR WORKPIECES USING  
A WORKPIECE-ENGAGING ELECTRODE ASSEMBLY WITH  
SEALING BOOT

Serial No.: 09/390,501

Filed: September 3, 1999

Examiner: Erica Smith-Hicks

Art Unit: 1741

6/B  
AB  
2/2/81

RESPONSE TO OFFICE ACTION DATED JULY 19, 2000

Assistant Commissioner for Patents  
Washington, D.C. 20231

Dear Sir:

In response to the Office Action mailed July 19, 2000, please amend the application  
in the following manner.

IN THE TITLE:

Please cancel the current title and insert the following title therefor:

-- CONTACT ASSEMBLY FOR SUPPLYING POWER TO WORKPIECES  
DURING ELECTROCHEMICAL PROCESSING --.

IN THE SPECIFICATION:

Please amend the specification, as follows:

RECEIVED  
JAN 25 2001  
TO 1741 MAIL ROOM

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